

Electronic Patent Application Fee Transmittal

Application Number:	10690782
Filing Date:	21-Oct-2003
Title of Invention:	METHOD FOR MANUFACTURING A WAFER LEVEL CHIP SCALE PACKAGE
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Filer:	Hosoon Lee/Stormi Davis
Attorney Docket Number:	9903-071

Filed as Large Entity

Utility Filing Fees

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Utility Appl issue fee	1501	1	1400	1400
Publ. Fee- early, voluntary, or normal	1504	1	300	300

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Extension-of-Time:				
Miscellaneous:				
Total in USD (\$)				1700